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## Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

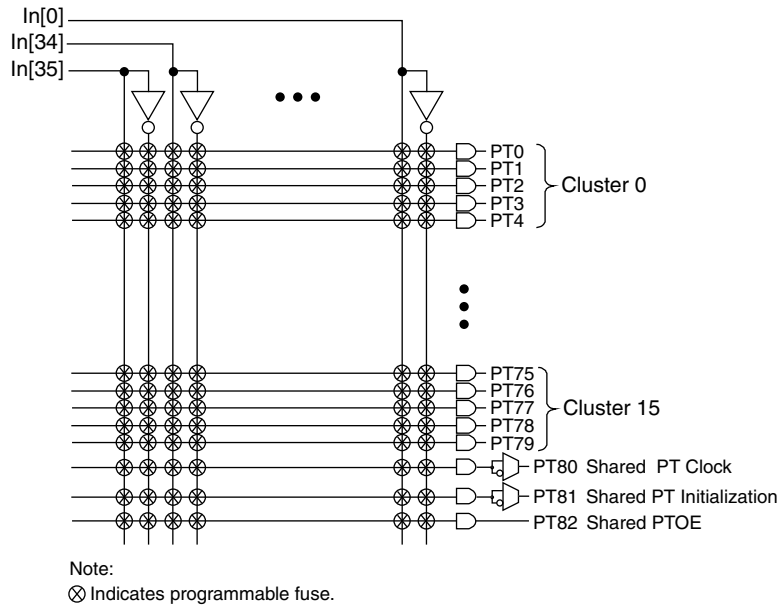
Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

## Applications of Embedded - CPLDs

### Details

Product Status	Active
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	1.7V ~ 1.9V
Number of Logic Elements/Blocks	4
Number of Macrocells	64
Number of Gates	-
Number of I/O	32
Operating Temperature	-40°C ~ 130°C (TJ)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4064zc-75tn48e">https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4064zc-75tn48e</a>

Figure 3. AND Array



### Enhanced Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in product term clusters. Each product term cluster is associated with a macrocell. The cluster size for the ispMACH 4000 family is 4+1 (total 5) product terms. The software automatically considers the availability and distribution of product term clusters as it fits the functions within a GLB. The logic allocator is designed to provide three speed paths: 5-PT fast bypass path, 20-PT Speed Locking path and an up to 80-PT path. The availability of these three paths lets designers trade timing variability for increased performance.

The enhanced Logic Allocator of the ispMACH 4000 family consists of the following blocks:

- Product Term Allocator
- Cluster Allocator
- Wide Steering Logic

Figure 4 shows a macrocell slice of the Logic Allocator. There are 16 such slices in the GLB.

Figure 4. Macrocell Slice

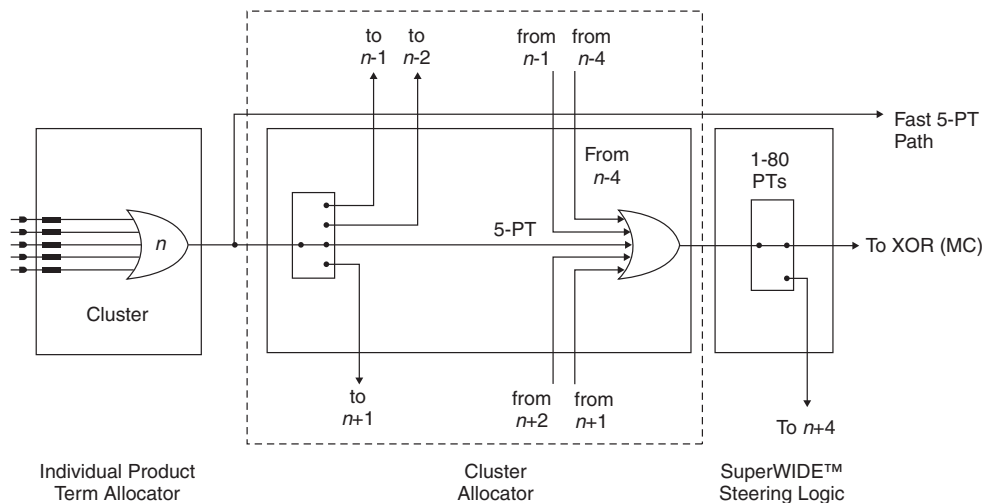
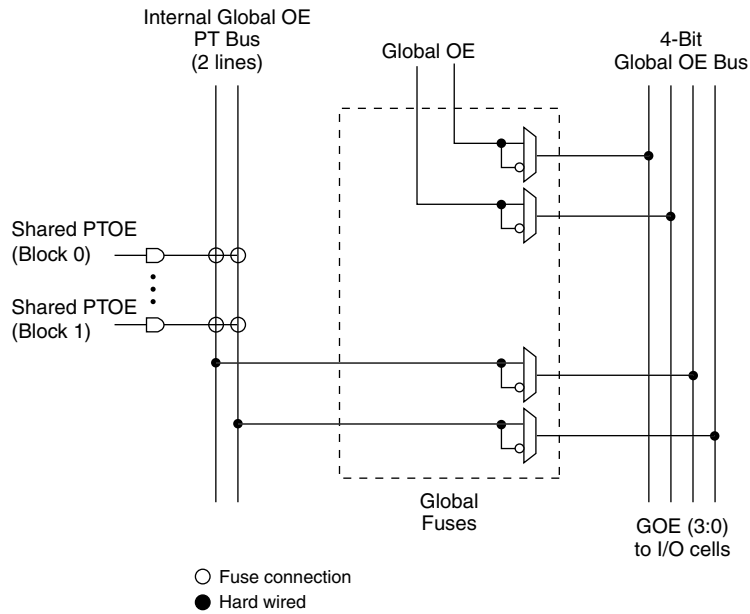


Figure 10. Global OE Generation for ispMACH 4032



## Zero Power/Low Power and Power Management

The ispMACH 4000 family is designed with high speed low power design techniques to offer both high speed and low power. With an advanced  $E^2$  low power cell and non sense-amplifier design approach (full CMOS logic approach), the ispMACH 4000 family offers SuperFAST pin-to-pin speeds, while simultaneously delivering low standby power without needing any “turbo bits” or other power management schemes associated with a traditional sense-amplifier approach.

The zero power ispMACH 4000Z is based on the 1.8V ispMACH 4000C family. With innovative circuit design changes, the ispMACH 4000Z family is able to achieve the industry’s “lowest static power”.

## IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 4000 devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port operates with an LVCMOS interface that corresponds to the power supply voltage.

## I/O Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os’ physical nature should be minimal so that board test time is minimized. The ispMACH 4000 family of devices allows this by offering the user the ability to quickly configure the physical nature of the I/O cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice’s ispVM<sup>®</sup> System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

## I/O Recommended Operating Conditions

Standard	$V_{CCO}$ (V) <sup>1</sup>	
	Min.	Max.
LVTTTL	3.0	3.6
LVC MOS 3.3	3.0	3.6
Extended LVC MOS 3.3 <sup>2</sup>	2.7	3.6
LVC MOS 2.5	2.3	2.7
LVC MOS 1.8	1.65	1.95
PCI 3.3	3.0	3.6

1. Typical values for  $V_{CCO}$  are the average of the min. and max. values.

2. ispMACH 4000Z only.

## DC Electrical Characteristics

### Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,4}$	Input Leakage Current (ispMACH 4000Z)	$0 \leq V_{IN} < V_{CCO}$	—	0.5	1	$\mu A$
$I_{IH}^1$	Input High Leakage Current (ispMACH 4000Z)	$V_{CCO} < V_{IN} \leq 5.5V$	—	—	10	$\mu A$
$I_{IL}, I_{IH}^1$	Input Leakage Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 3.6V, T_j = 105^\circ C$	—	—	10	$\mu A$
		$0 \leq V_{IN} \leq 3.6V, T_j = 130^\circ C$	—	—	15	$\mu A$
$I_{IH}^{1,2}$	Input High Leakage Current (ispMACH 4000V/B/C)	$3.6V < V_{IN} \leq 5.5V, T_j = 105^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V^1$	—	—	20	$\mu A$
		$3.6V < V_{IN} \leq 5.5V, T_j = 130^\circ C$ $3.0V \leq V_{CCO} \leq 3.6V^1$	—	—	50	$\mu A$
$I_{PU}$	I/O Weak Pull-up Resistor Current (ispMACH 4000Z)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-150	$\mu A$
	I/O Weak Pull-up Resistor Current (ispMACH 4000V/B/C)	$0 \leq V_{IN} \leq 0.7V_{CCO}$	-30	—	-200	$\mu A$
$I_{PD}$	I/O Weak Pull-down Resistor Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MIN)$	30	—	150	$\mu A$
$I_{BHLS}$	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (MAX)$	30	—	—	$\mu A$
$I_{BHHS}$	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCO}$	-30	—	—	$\mu A$
$I_{BHLO}$	Bus Hold Low Overdrive Current	$0V \leq V_{IN} \leq V_{BHT}$	—	—	150	$\mu A$
$I_{BHHO}$	Bus Hold High Overdrive Current	$V_{BHT} \leq V_{IN} \leq V_{CCO}$	—	—	-150	$\mu A$
$V_{BHT}$	Bus Hold Trip Points	—	$V_{CCO} * 0.35$	—	$V_{CCO} * 0.65$	V
$C_1$	I/O Capacitance <sup>3</sup>	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	8	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (MAX)$	—		—	
$C_2$	Clock Capacitance <sup>3</sup>	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	6	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (MAX)$	—		—	
$C_3$	Global Input Capacitance <sup>3</sup>	$V_{CCO} = 3.3V, 2.5V, 1.8V$	—	6	—	pf
		$V_{CC} = 1.8V, V_{IO} = 0$ to $V_{IH} (MAX)$	—		—	

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.

2. 5V tolerant inputs and I/O should only be placed in banks where  $3.0V \leq V_{CCO} \leq 3.6V$ .

3.  $T_A = 25^\circ C, f = 1.0MHz$

4.  $I_{IH}$  excursions of up to 1.5 $\mu A$  maximum per pin above the spec limit may be observed for certain voltage conditions on no more than 10% of the device's I/O pins.

## Supply Current, ispMACH 4000V/B/C

## Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>ispMACH 4032V/B/C</b>						
ICC <sup>1,2,3</sup>	Operating Power Supply Current	V <sub>CC</sub> = 3.3V	—	11.8	—	mA
		V <sub>CC</sub> = 2.5V	—	11.8	—	mA
		V <sub>CC</sub> = 1.8V	—	1.8	—	mA
ICC <sup>4</sup>	Standby Power Supply Current	V <sub>CC</sub> = 3.3V	—	11.3	—	mA
		V <sub>CC</sub> = 2.5V	—	11.3	—	mA
		V <sub>CC</sub> = 1.8V	—	1.3	—	mA
<b>ispMACH 4064V/B/C</b>						
ICC <sup>1,2,3</sup>	Operating Power Supply Current	V <sub>CC</sub> = 3.3V	—	12	—	mA
		V <sub>CC</sub> = 2.5V	—	12	—	mA
		V <sub>CC</sub> = 1.8V	—	2	—	mA
ICC <sup>5</sup>	Standby Power Supply Current	V <sub>CC</sub> = 3.3V	—	11.5	—	mA
		V <sub>CC</sub> = 2.5V	—	11.5	—	mA
		V <sub>CC</sub> = 1.8V	—	1.5	—	mA
<b>ispMACH 4128V/B/C</b>						
ICC <sup>1,2,3</sup>	Operating Power Supply Current	V <sub>CC</sub> = 3.3V	—	12	—	mA
		V <sub>CC</sub> = 2.5V	—	12	—	mA
		V <sub>CC</sub> = 1.8V	—	2	—	mA
ICC <sup>4</sup>	Standby Power Supply Current	V <sub>CC</sub> = 3.3V	—	11.5	—	mA
		V <sub>CC</sub> = 2.5V	—	11.5	—	mA
		V <sub>CC</sub> = 1.8V	—	1.5	—	mA
<b>ispMACH 4256V/B/C</b>						
I <sub>CC</sub> <sup>1,2,3</sup>	Operating Power Supply Current	V <sub>CC</sub> = 3.3V	—	12.5	—	mA
		V <sub>CC</sub> = 2.5V	—	12.5	—	mA
		V <sub>CC</sub> = 1.8V	—	2.5	—	mA
I <sub>CC</sub> <sup>4</sup>	Standby Power Supply Current	V <sub>CC</sub> = 3.3V	—	12	—	mA
		V <sub>CC</sub> = 2.5V	—	12	—	mA
		V <sub>CC</sub> = 1.8V	—	2	—	mA
<b>ispMACH 4384V/B/C</b>						
I <sub>CC</sub> <sup>1,2,3</sup>	Operating Power Supply Current	V <sub>CC</sub> = 3.3V	—	13.5	—	mA
		V <sub>CC</sub> = 2.5V	—	13.5	—	mA
		V <sub>CC</sub> = 1.8V	—	3.5	—	mA
I <sub>CC</sub> <sup>4</sup>	Standby Power Supply Current	V <sub>CC</sub> = 3.3V	—	12.5	—	mA
		V <sub>CC</sub> = 2.5V	—	12.5	—	mA
		V <sub>CC</sub> = 1.8V	—	2.5	—	mA
<b>ispMACH 4512V/B/C</b>						
I <sub>CC</sub> <sup>1,2,3</sup>	Operating Power Supply Current	V <sub>CC</sub> = 3.3V	—	14	—	mA
		V <sub>CC</sub> = 2.5V	—	14	—	mA
		V <sub>CC</sub> = 1.8V	—	4	—	mA

**Supply Current, ispMACH 4000Z (Cont.)**

**Over Recommended Operating Conditions**

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>ispMACH 4256ZC</b>						
ICC <sup>1,2,3,5</sup>	Operating Power Supply Current	V <sub>CC</sub> = 1.8V, T <sub>A</sub> = 25°C	—	341	—	μA
		V <sub>CC</sub> = 1.9V, T <sub>A</sub> = 70°C	—	361	—	μA
		V <sub>CC</sub> = 1.9V, T <sub>A</sub> = 85°C	—	372	—	μA
		V <sub>CC</sub> = 1.9V, T <sub>A</sub> = 125°C	—	468	—	μA
ICC <sup>4,5</sup>	Standby Power Supply Current	V <sub>CC</sub> = 1.8V, T <sub>A</sub> = 25°C	—	13	—	μA
		V <sub>CC</sub> = 1.9V, T <sub>A</sub> = 70°C	—	32	55	μA
		V <sub>CC</sub> = 1.9V, T <sub>A</sub> = 85°C	—	43	90	μA
		V <sub>CC</sub> = 1.9V, T <sub>A</sub> = 125°C	—	135	—	μA

1. T<sub>A</sub> = 25°C, frequency = 1.0 MHz.
2. Device configured with 16-bit counters.
3. I<sub>CC</sub> varies with specific device configuration and operating frequency.
4. V<sub>CCO</sub> = 3.6V, V<sub>IN</sub> = 0V or V<sub>CCO</sub>, bus maintenance turned off. V<sub>IN</sub> above V<sub>CCO</sub> will add transient current above the specified standby I<sub>CC</sub>.
5. Includes V<sub>CCO</sub> current without output loading.

## I/O DC Electrical Characteristics

### Over Recommended Operating Conditions

Standard	$V_{IL}$		$V_{IH}$		$V_{OL}$ Max (V)	$V_{OH}$ Min (V)	$I_{OL}^1$ (mA)	$I_{OH}^1$ (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LVTTTL	-0.3	0.80	2.0	5.5	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 3.3	-0.3	0.80	2.0	5.5	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 2.5	-0.3	0.70	1.70	3.6	0.40	$V_{CCO} - 0.40$	8.0	-4.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 1.8 (4000V/B)	-0.3	0.63	1.17	3.6	0.40	$V_{CCO} - 0.45$	2.0	-2.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
LVCMOS 1.8 (4000C/Z)	-0.3	$0.35 * V_{CC}$	$0.65 * V_{CC}$	3.6	0.40	$V_{CCO} - 0.45$	2.0	-2.0
					0.20	$V_{CCO} - 0.20$	0.1	-0.1
PCI 3.3 (4000V/B)	-0.3	1.08	1.5	5.5	$0.1 V_{CCO}$	$0.9 V_{CCO}$	1.5	-0.5
PCI 3.3 (4000C/Z)	-0.3	$0.3 * 3.3 * (V_{CC} / 1.8)$	$0.5 * 3.3 * (V_{CC} / 1.8)$	5.5	$0.1 V_{CCO}$	$0.9 V_{CCO}$	1.5	-0.5

1. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed  $n * 8mA$ . Where  $n$  is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

## ispMACH 4000V/B/C External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description <sup>1, 2, 3</sup>	-25		-27		-3		-35		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>PD</sub>	5-PT bypass combinatorial propagation delay	—	2.5	—	2.7	—	3.0	—	3.5	ns
t <sub>PD_MC</sub>	20-PT combinatorial propagation delay through macrocell	—	3.2	—	3.5	—	3.8	—	4.2	ns
t <sub>S</sub>	GLB register setup time before clock	1.8	—	1.8	—	2.0	—	2.0	—	ns
t <sub>ST</sub>	GLB register setup time before clock with T-type register	2.0	—	2.0	—	2.2	—	2.2	—	ns
t <sub>SIR</sub>	GLB register setup time before clock, input register path	0.7	—	1.0	—	1.0	—	1.0	—	ns
t <sub>SIRZ</sub>	GLB register setup time before clock with zero hold	1.7	—	2.0	—	2.0	—	2.0	—	ns
t <sub>H</sub>	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	0.0	—	ns
t <sub>HT</sub>	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	0.0	—	ns
t <sub>HIR</sub>	GLB register hold time after clock, input register path	0.9	—	1.0	—	1.0	—	1.0	—	ns
t <sub>HIRZ</sub>	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	0.0	—	ns
t <sub>CO</sub>	GLB register clock-to-output delay	—	2.2	—	2.7	—	2.7	—	2.7	ns
t <sub>R</sub>	External reset pin to output delay	—	3.5	—	4.0	—	4.4	—	4.5	ns
t <sub>RW</sub>	External reset pulse duration	1.5	—	1.5	—	1.5	—	1.5	-	ns
t <sub>P<sub>TOE/DIS</sub></sub>	Input to output local product term output enable/disable	—	4.0	—	4.5	—	5.0	—	5.5	ns
t <sub>G<sub>P</sub>TOE/DIS</sub>	Input to output global product term output enable/disable	—	5.0	—	6.5	—	8.0	—	8.0	ns
t <sub>GOE/DIS</sub>	Global OE input to output enable/disable	—	3.0	—	3.5	—	4.0	—	4.5	ns
t <sub>CW</sub>	Global clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
t <sub>GW</sub>	Global gate width low (for low transparent) or high (for high transparent)	1.1	—	1.3	—	1.3	—	1.3	—	ns
t <sub>WIR</sub>	Input register clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
f <sub>MAX</sub> <sup>4</sup>	Clock frequency with internal feedback	—	400	—	333	—	322	—	322	MHz
f <sub>MAX</sub> (Ext.)	Clock frequency with external feedback, [1/ (t <sub>S</sub> + t <sub>CO</sub> )]	—	250	—	222	—	212	—	212	MHz

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.3.2

2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

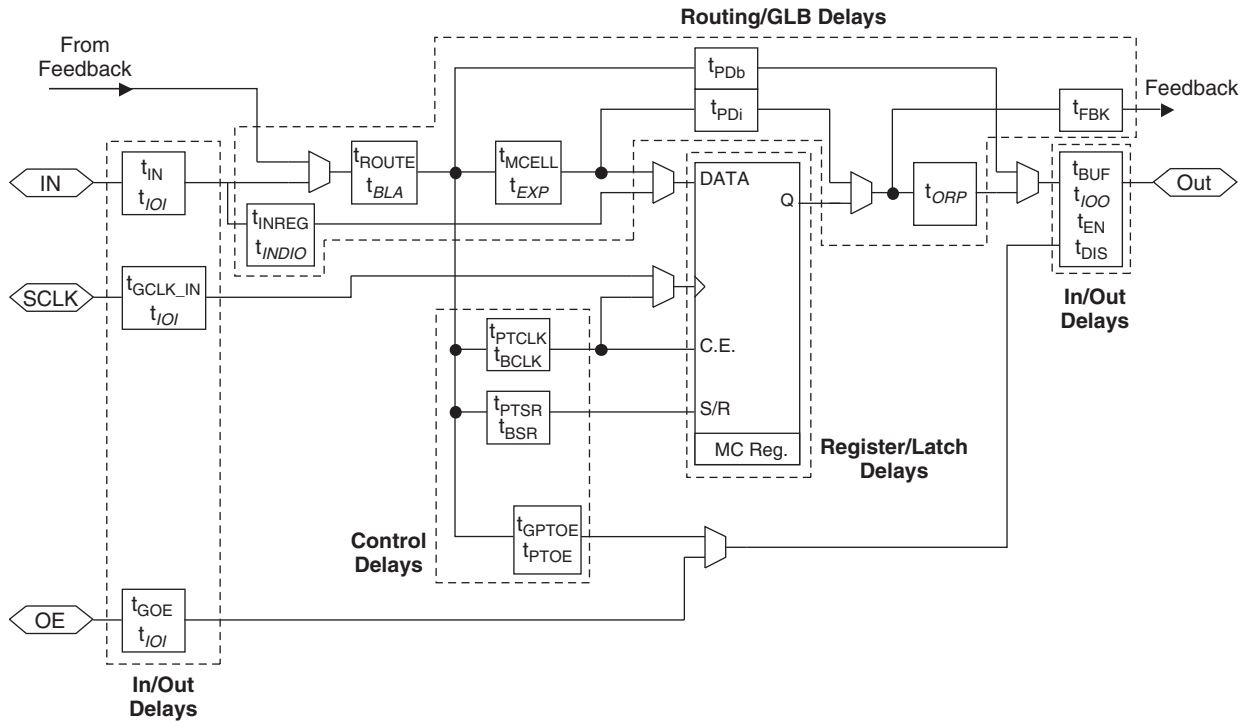
4. Standard 16-bit counter using GRP feedback.



## Timing Model

The task of determining the timing through the ispMACH 4000 family, like any CPLD, is relatively simple. The timing model provided in Figure 11 shows the specific delay paths. Once the implementation of a given function is determined either conceptually or from the software report file, the delay path of the function can easily be determined from the timing model. The Lattice design tools report the timing delays based on the same timing model for a particular design. Note that the internal timing parameters are given for reference only, and are not tested. The external timing parameters are tested and guaranteed for every device. For more information on the timing model and usage, refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#).

Figure 11. ispMACH 4000 Timing Model



Note: Italicized items are optional delay adders.

ispMACH 4000V/B/C Timing Adders<sup>1</sup>

Adder Type	Base Parameter	Description	-25		-27		-3		-35		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>Optional Delay Adders</b>											
t <sub>INDIO</sub>	t <sub>INREG</sub>	Input register delay	—	0.95	—	1.00	—	1.00	—	1.00	ns
t <sub>EXP</sub>	t <sub>MCELL</sub>	Product term expander delay	—	0.33	—	0.33	—	0.33	—	0.33	ns
t <sub>ORP</sub>	—	Output routing pool delay	—	0.05	—	0.05	—	0.05	—	0.05	ns
t <sub>BLA</sub>	t <sub>ROUTE</sub>	Additional block loading adder	—	0.03	—	0.05	—	0.05	—	0.05	ns
<b>t<sub>IOI</sub> Input Adjusters</b>											
LVTTTL_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVTTTL standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVC MOS33_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVC MOS 3.3 standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVC MOS25_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVC MOS 2.5 standard	—	0.60	—	0.60	—	0.60	—	0.60	ns
LVC MOS18_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVC MOS 1.8 standard	—	0.00	—	0.00	—	0.00	—	0.00	ns
PCI_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using PCI compatible input	—	0.60	—	0.60	—	0.60	—	0.60	ns
<b>t<sub>IOO</sub> Output Adjusters</b>											
LVTTTL_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
LVC MOS33_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
LVC MOS25_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	—	0.10	ns
LVC MOS18_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	—	0.00	ns
PCI_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t <sub>BUF</sub> , t <sub>EN</sub>	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

Timing v.3.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

**ispMACH 4000Z Timing Adders (Cont.)<sup>1</sup>**

Adder Type	Base Parameter	Description	-45		-5		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
<b>Optional Delay Adders</b>									
t <sub>INDIO</sub>	t <sub>INREG</sub>	Input register delay	—	1.30	—	1.30	—	1.30	ns
t <sub>EXP</sub>	t <sub>MCELL</sub>	Product term expander delay	—	0.45	—	0.45	—	0.50	ns
t <sub>ORP</sub>	—	Output routing pool delay	—	0.40	—	0.40	—	0.40	ns
t <sub>BLA</sub>	t <sub>ROUTE</sub>	Additional block loading adder	—	0.05	—	0.05	—	0.05	ns
<b>t<sub>IOI</sub> Input Adjusters</b>									
LVTTTL_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVTTTL standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS33_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVC MOS 3.3 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS25_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVC MOS 2.5 standard	—	0.60	—	0.60	—	0.60	ns
LVC MOS18_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using LVC MOS 1.8 standard	—	0.00	—	0.00	—	0.00	ns
PCI_in	t <sub>IN</sub> , t <sub>GCLK_IN</sub> , t <sub>GOE</sub>	Using PCI compatible input	—	0.60	—	0.60	—	0.60	ns
<b>t<sub>IOO</sub> Output Adjusters</b>									
LVTTTL_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as TTL buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS33_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as 3.3V buffer	—	0.20	—	0.20	—	0.20	ns
LVC MOS25_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as 2.5V buffer	—	0.10	—	0.10	—	0.10	ns
LVC MOS18_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as 1.8V buffer	—	0.00	—	0.00	—	0.00	ns
PCI_out	t <sub>BUF</sub> , t <sub>EN</sub> , t <sub>DIS</sub>	Output configured as PCI compatible buffer	—	0.20	—	0.20	—	0.20	ns
Slow Slew	t <sub>BUF</sub> , t <sub>EN</sub>	Output configured for slow slew rate	—	1.00	—	1.00	—	1.00	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

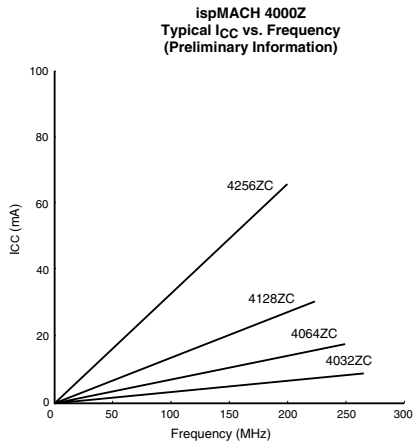
Timing v.2.2

1. Refer to TN1004, [ispMACH 4000 Timing Model Design and Usage Guidelines](#) for information regarding use of these adders.

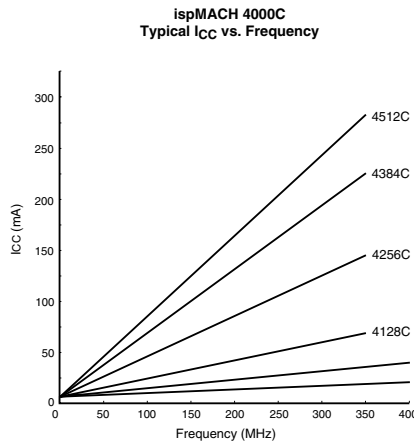
## Boundary Scan Waveforms and Timing Specifications

Symbol	Parameter	Min.	Max.	Units
$t_{BTCP}$	TCK [BSCAN test] clock cycle	40	—	ns
$t_{BTCH}$	TCK [BSCAN test] pulse width high	20	—	ns
$t_{BTCL}$	TCK [BSCAN test] pulse width low	20	—	ns
$t_{BTSU}$	TCK [BSCAN test] setup time	8	—	ns
$t_{BTH}$	TCK [BSCAN test] hold time	10	—	ns
$t_{BRF}$	TCK [BSCAN test] rise and fall time	50	—	mV/ns
$t_{BTCO}$	TAP controller falling edge of clock to valid output	—	10	ns
$t_{BTOZ}$	TAP controller falling edge of clock to data output disable	—	10	ns
$t_{BTVO}$	TAP controller falling edge of clock to data output enable	—	10	ns
$t_{BTCPSU}$	BSCAN test Capture register setup time	8	—	ns
$t_{BTCPH}$	BSCAN test Capture register hold time	10	—	ns
$t_{BTUCO}$	BSCAN test Update reg, falling edge of clock to valid output	—	25	ns
$t_{BTUOZ}$	BSCAN test Update reg, falling edge of clock to output disable	—	25	ns
$t_{BTUOV}$	BSCAN test Update reg, falling edge of clock to output enable	—	25	ns

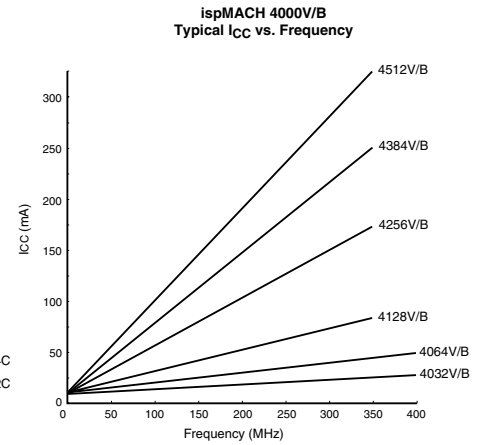
## Power Consumption



Note: The devices are configured with maximum number of 16-bit counters, typical current at 1.8V, 25°C.



Note: The devices are configured with maximum number of 16-bit counters, typical current at 1.8V, 25°C.



Note: The devices are configured with maximum number of 16-bit counters, typical current at 3.3V, 2.5V, 25°C.

## Power Estimation Coefficients<sup>1</sup>

Device	A	B
ispMACH 4032V/B	11.3	0.010
ispMACH 4032C	1.3	0.010
ispMACH 4064V/B	11.5	0.010
ispMACH 4064C	1.5	0.010
ispMACH 4128V/B	11.5	0.011
ispMACH 4128C	1.5	0.011
ispMACH 4256V/B	12	0.011
ispMACH 4256C	2	0.011
ispMACH 4384V/B	12.5	0.013
ispMACH 4384C	2.5	0.013
ispMACH 4512V/B	13	0.013
ispMACH 4512C	3	0.013
ispMACH 4032ZC	0.010	0.010
ispMACH 4064ZC	0.011	0.010
ispMACH 4128ZC	0.012	0.010
ispMACH 4256ZC	0.013	0.010

1. For further information about the use of these coefficients, refer to TN1005, [Power Estimation in ispMACH 4000V/B/C/Z Devices](#).

**ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
19	0	C13	C^10
20	0	C12	C^9
21	0	C10	C^8
22	0	C9	C^7
23	0	C8	C^6
24	0	GND (Bank 0)	-
25	0	C6	C^5
26	0	C5	C^4
27	0	C4	C^3
28	0	C2	C^2
29	0	C0	C^0
30	0	VCCO (Bank 0)	-
31	0	TCK	-
32	0	VCC	-
33	0	GND	-
34	0	D14	D^11
35	0	D13	D^10
36	0	D12	D^9
37	0	D10	D^8
38	0	D9	D^7
39	0	D8	D^6
40	0	GND (Bank 0)	-
41	0	VCCO (Bank 0)	-
42	0	D6	D^5
43	0	D5	D^4
44	0	D4	D^3
45	0	D2	D^2
46	0	D1	D^1
47	0	D0	D^0
48	0	CLK1/I	-
49	1	GND (Bank 1)	-
50	1	CLK2/I	-
51	1	VCC	-
52	1	E0	E^0
53	1	E1	E^1
54	1	E2	E^2
55	1	E4	E^3
56	1	E5	E^4
57	1	E6	E^5
58	1	VCCO (Bank 1)	-
59	1	GND (Bank 1)	-
60	1	E8	E^6
61	1	E9	E^7

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:  
132-Ball csBGA (Cont.)**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
E3	0	NC	-	B8	B^6	D12	D^6
F2	0	A12	A^12	B9	B^7	D10	D^5
F1	0	A13	A^13	B10	B^8	D8	D^4
F3	0	A14	A^14	B12	B^9	D6	D^3
G1	0	A15	A^15	B13	B^10	D4	D^2
G2	0	I	-	B14	B^11	D2	D^1
G3	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
H2	0	NC	-	C14	C^11	E2	E^1
H1	0	B15	B^15	C13	C^10	E4	E^2
H3	0	B14	B^14	C12	C^9	E6	E^3
J1	0	B13	B^13	C10	C^8	E8	E^4
J2	0	B12	B^12	C9	C^7	E10	E^5
J3	0	NC	-	C8	C^6	E12	E^6
K2	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
K1	0	NC	-	C6	C^5	F2	F^1
K3	0	B11	B^11	C5	C^4	F4	F^2
L2	0	B10	B^10	C4	C^3	F6	F^3
L1	0	B9	B^9	C2	C^2	F8	F^4
L3	0	B8	B^8	C1	C^1	F10	F^5
M1	0	I	-	C0	C^0	F12	F^6
M2	0	NC	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
N1	-	TCK	-	TCK	-	TCK	-
P1	-	VCC	-	VCC	-	VCC	-
P2	-	GND	-	GND	-	GND	-
N2	0	I	-	D14	D^11	G12	G^6
P3	0	B7	B^7	D13	D^10	G10	G^5
M3	0	B6	B^6	D12	D^9	G8	G^4
N3	0	B5	B^5	D10	D^8	G6	G^3
P4	0	B4	B^4	D9	D^7	G4	G^2
M4	0	NC	-	D8	D^6	G2	G^1
N4	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
P5	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
N5	0	NC	-	D6	D^5	H12	H^6
M5	0	B3	B^3	D5	D^4	H10	H^5
N6	0	B2	B^2	D4	D^3	H8	H^4
P6	0	B1	B^1	D2	D^2	H6	H^3
M6	0	B0	B^0	D1	D^1	H4	H^2
P7	0	NC	-	D0	D^0	H2	H^1
N7	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
M7	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
N8	-	VCC	-	VCC	-	VCC	-

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:  
256-Ball ftBGA/fpBGA**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
-	-	-	-	-	-	VCC	-	VCC	-
-	-	GND	-	GND	-	GND	-	GND	-
C3	-	TDI	-	TDI	-	TDI	-	TDI	-
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
B1	0	C14	C^7	C14	C^9	C14	C^7	C14	C^7
F5	0	C12	C^6	C12	C^8	C12	C^6	C12	C^6
D3	0	C10	C^5	C10	C^7	C10	C^5	C10	C^5
C1	0	C8	C^4	C9	C^6	C8	C^4	C8	C^4
C2	0	C6	C^3	C8	C^5	C6	C^3	C6	C^3
E3	0	C4	C^2	C6	C^4	C4	C^2	C4	C^2
D2	0	C2	C^1	C4	C^3	C2	C^1	C2	C^1
F6	0	C0	C^0	C2	C^2	C0	C^0	C0	C^0
D1	0	NC	-	C1	C^1	F6	F^3	H0	H^0
E2	0	NC	-	C0	C^0	F4	F^2	H4	H^1
E4	0	NC	-	NC	-	D6	D^3	F4	F^2
G5	0	NC	-	NC	-	D4	D^2	F6	F^3
E1	0	NC	-	NC	-	NC	-	F8	F^4
-	0	-	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
F2	0	NC	-	NC	-	NC	-	F10	F^5
F1	0	NC	-	NC	-	D2	D^1	F12	F^6
G1	0	NC	-	NC	-	D0	D^0	F14	F^7
G6	0	NC	-	D14	D^9	F2	F^1	H8	H^2
G4	0	NC	-	D12	D^8	F0	F^0	H12	H^3
H6	0	D14	D^7	D10	D^7	E14	E^7	G14	G^7
G3	0	D12	D^6	D9	D^6	E12	E^6	G12	G^6
H5	0	D10	D^5	D8	D^5	E10	E^5	G10	G^5
G2	0	D8	D^4	D6	D^4	E8	E^4	G8	G^4
H1	0	D6	D^3	D4	D^3	E6	E^3	G6	G^3
H2	0	D4	D^2	D2	D^2	E4	E^2	G4	G^2
H3	0	D2	D^1	D1	D^1	E2	E^1	G2	G^1
H4	0	D0	D^0	D0	D^0	E0	E^0	G0	G^0
-	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
-	0	-	-	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
J4	0	E0	E^0	E0	E^0	H0	H^0	J0	J^0
J3	0	E2	E^1	E1	E^1	H2	H^1	J2	J^1
J2	0	E4	E^2	E2	E^2	H4	H^2	J4	J^2
J1	0	E6	E^3	E4	E^3	H6	H^3	J6	J^3
K1	0	E8	E^4	E6	E^4	H8	H^4	J8	J^4
J5	0	E10	E^5	E8	E^5	H10	H^5	J10	J^5
K2	0	E12	E^6	E9	E^6	H12	H^6	J12	J^6



## ispMACH 4000B (2.5V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032B	LC4032B-5T48I	32	2.5	5	TQFP	48	32	I
	LC4032B-75T48I	32	2.5	7.5	TQFP	48	32	I
	LC4032B-10T48I	32	2.5	10	TQFP	48	32	I
	LC4032B-5T44I	32	2.5	5	TQFP	44	30	I
	LC4032B-75T44I	32	2.5	7.5	TQFP	44	30	I
	LC4032B-10T44I	32	2.5	10	TQFP	44	30	I
LC4064B	LC4064B-5T100I	64	2.5	5	TQFP	100	64	I
	LC4064B-75T100I	64	2.5	7.5	TQFP	100	64	I
	LC4064B-10T100I	64	2.5	10	TQFP	100	64	I
	LC4064B-5T48I	64	2.5	5	TQFP	48	32	I
	LC4064B-75T48I	64	2.5	7.5	TQFP	48	32	I
	LC4064B-10T48I	64	2.5	10	TQFP	48	32	I
	LC4064B-5T44I	64	2.5	5	TQFP	44	30	I
	LC4064B-75T44I	64	2.5	7.5	TQFP	44	30	I
LC4128B	LC4128B-5T128I	128	2.5	5	TQFP	128	92	I
	LC4128B-75T128I	128	2.5	7.5	TQFP	128	92	I
	LC4128B-10T128I	128	2.5	10	TQFP	128	92	I
	LC4128B-5T100I	128	2.5	5	TQFP	100	64	I
	LC4128B-75T100I	128	2.5	7.5	TQFP	100	64	I
	LC4128B-10T100I	128	2.5	10	TQFP	100	64	I
LC4256B	LC4256B-5FT256AI	256	2.5	5	ftBGA	256	128	I
	LC4256B-75FT256AI	256	2.5	7.5	ftBGA	256	128	I
	LC4256B-10FT256AI	256	2.5	10	ftBGA	256	128	I
	LC4256B-5FT256BI	256	2.5	5	ftBGA	256	160	I
	LC4256B-75FT256BI	256	2.5	7.5	ftBGA	256	160	I
	LC4256B-10FT256BI	256	2.5	10	ftBGA	256	160	I
	LC4256B-5F256AI <sup>1</sup>	256	2.5	5	fpBGA	256	128	I
	LC4256B-75F256AI <sup>1</sup>	256	2.5	7.5	fpBGA	256	128	I
	LC4256B-10F256AI <sup>1</sup>	256	2.5	10	fpBGA	256	128	I
	LC4256B-5F256BI <sup>1</sup>	256	2.5	5	fpBGA	256	160	I
	LC4256B-75F256BI <sup>1</sup>	256	2.5	7.5	fpBGA	256	160	I
	LC4256B-10F256BI <sup>1</sup>	256	2.5	10	fpBGA	256	160	I
	LC4256B-5T176I	256	2.5	5	TQFP	176	128	I
	LC4256B-75T176I	256	2.5	7.5	TQFP	176	128	I
	LC4256B-10T176I	256	2.5	10	TQFP	176	128	I
	LC4256B-5T100I	256	2.5	5	TQFP	100	64	I
	LC4256B-75T100I	256	2.5	7.5	TQFP	100	64	I
	LC4256B-10T100I	256	2.5	10	TQFP	100	64	I

## ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4512V	LC4512V-35FT256C	512	3.3	3.5	ftBGA	256	208	C
	LC4512V-5FT256C	512	3.3	5	ftBGA	256	208	C
	LC4512V-75FT256C	512	3.3	7.5	ftBGA	256	208	C
	LC4512V-35F256C <sup>1</sup>	512	3.3	3.5	fpBGA	256	208	C
	LC4512V-5F256C <sup>1</sup>	512	3.3	5	fpBGA	256	208	C
	LC4512V-75F256C <sup>1</sup>	512	3.3	7.5	fpBGA	256	208	C
	LC4512V-35T176C	512	3.3	3.5	TQFP	176	128	C
	LC4512V-5T176C	512	3.3	5	TQFP	176	128	C
	LC4512V-75T176C	512	3.3	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

## ispMACH 4000V (3.3V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-5T48I	32	3.3	5	TQFP	48	32	I
	LC4032V-75T48I	32	3.3	7.5	TQFP	48	32	I
	LC4032V-10T48I	32	3.3	10	TQFP	48	32	I
	LC4032V-5T44I	32	3.3	5	TQFP	44	30	I
	LC4032V-75T44I	32	3.3	7.5	TQFP	44	30	I
	LC4032V-10T44I	32	3.3	10	TQFP	44	30	I
LC4064V	LC4064V-5T100I	64	3.3	5	TQFP	100	64	I
	LC4064V-75T100I	64	3.3	7.5	TQFP	100	64	I
	LC4064V-10T100I	64	3.3	10	TQFP	100	64	I
	LC4064V-5T48I	64	3.3	5	TQFP	48	32	I
	LC4064V-75T48I	64	3.3	7.5	TQFP	48	32	I
	LC4064V-10T48I	64	3.3	10	TQFP	48	32	I
	LC4064V-5T44I	64	3.3	5	TQFP	44	30	I
	LC4064V-75T44I	64	3.3	7.5	TQFP	44	30	I
	LC4064V-10T44I	64	3.3	10	TQFP	44	30	I
LC4128V	LC4128V-5T144I	128	3.3	5	TQFP	144	96	I
	LC4128V-75T144I	128	3.3	7.5	TQFP	144	96	I
	LC4128V-10T144I	128	3.3	10	TQFP	144	96	I
	LC4128V-5T128I	128	3.3	5	TQFP	128	92	I
	LC4128V-75T128I	128	3.3	7.5	TQFP	128	92	I
	LC4128V-10T128I	128	3.3	10	TQFP	128	92	I
	LC4128V-5T100I	128	3.3	5	TQFP	100	64	I
	LC4128V-75T100I	128	3.3	7.5	TQFP	100	64	I
	LC4128V-10T100I	128	3.3	10	TQFP	100	64	I

## ispMACH 4000V (3.3V) Industrial Devices (Cont.)

Family	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4256V	LC4256V-5FT256AI	256	3.3	5	ftBGA	256	128	I
	LC4256V-75FT256AI	256	3.3	7.5	ftBGA	256	128	I
	LC4256V-10FT256AI	256	3.3	10	ftBGA	256	128	I
	LC4256V-5FT256BI	256	3.3	5	ftBGA	256	160	I
	LC4256V-75FT256BI	256	3.3	7.5	ftBGA	256	160	I
	LC4256V-10FT256BI	256	3.3	10	ftBGA	256	160	I
	LC4256V-5F256AI <sup>1</sup>	256	3.3	5	fpBGA	256	128	I
	LC4256V-75F256AI <sup>1</sup>	256	3.3	7.5	fpBGA	256	128	I
	LC4256V-10F256AI <sup>1</sup>	256	3.3	10	fpBGA	256	128	I
	LC4256V-5F256BI <sup>1</sup>	256	3.3	5	fpBGA	256	160	I
	LC4256V-75F256BI <sup>1</sup>	256	3.3	7.5	fpBGA	256	160	I
	LC4256V-10F256BI <sup>1</sup>	256	3.3	10	fpBGA	256	160	I
	LC4256V-5T176I	256	3.3	5	TQFP	176	128	I
	LC4256V-75T176I	256	3.3	7.5	TQFP	176	128	I
	LC4256V-10T176I	256	3.3	10	TQFP	176	128	I
	LC4256V-5T144I	256	3.3	5	TQFP	144	96	I
	LC4256V-75T144I	256	3.3	7.5	TQFP	144	96	I
	LC4256V-10T144I	256	3.3	10	TQFP	144	96	I
	LC4256V-5T100I	256	3.3	5	TQFP	100	64	I
	LC4256V-75T100I	256	3.3	7.5	TQFP	100	64	I
LC4256V-10T100I	256	3.3	10	TQFP	100	64	I	
LC4384V	LC4384V-5FT256I	384	3.3	5	ftBGA	256	192	I
	LC4384V-75FT256I	384	3.3	7.5	ftBGA	256	192	I
	LC4384V-10FT256I	384	3.3	10	ftBGA	256	192	I
	LC4384V-5F256I <sup>1</sup>	384	3.3	5	fpBGA	256	192	I
	LC4384V-75F256I <sup>1</sup>	384	3.3	7.5	fpBGA	256	192	I
	LC4384V-10F256I <sup>1</sup>	384	3.3	10	fpBGA	256	192	I
	LC4384V-5T176I	384	3.3	5	TQFP	176	128	I
	LC4384V-75T176I	384	3.3	7.5	TQFP	176	128	I
	LC4384V-10T176I	384	3.3	10	TQFP	176	128	I
LC4512V	LC4512V-5FT256I	512	3.3	5	ftBGA	256	208	I
	LC4512V-75FT256I	512	3.3	7.5	ftBGA	256	208	I
	LC4512V-10FT256I	512	3.3	10	ftBGA	256	208	I
	LC4512V-5F256I <sup>1</sup>	512	3.3	5	fpBGA	256	208	I
	LC4512V-75F256I <sup>1</sup>	512	3.3	7.5	fpBGA	256	208	I
	LC4512V-10F256I <sup>1</sup>	512	3.3	10	fpBGA	256	208	I
	LC4512V-5T176I	512	3.3	5	TQFP	176	128	I
	LC4512V-75T176I	512	3.3	7.5	TQFP	176	128	I
	LC4512V-10T176I	512	3.3	10	TQFP	176	128	I

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

## ispMACH 4000V (3.3V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-25TN48C	32	3.3	2.5	Lead-free TQFP	48	32	C
	LC4032V-5TN48C	32	3.3	5	Lead-free TQFP	48	32	C
	LC4032V-75TN48C	32	3.3	7.5	Lead-free TQFP	48	32	C
	LC4032V-25TN44C	32	3.3	2.5	Lead-free TQFP	44	30	C
	LC4032V-5TN44C	32	3.3	5	Lead-free TQFP	44	30	C
	LC4032V-75TN44C	32	3.3	7.5	Lead-free TQFP	44	30	C
LC4064V	LC4064V-25TN100C	64	3.3	2.5	Lead-free TQFP	100	64	C
	LC4064V-5TN100C	64	3.3	5	Lead-free TQFP	100	64	C
	LC4064V-75TN100C	64	3.3	7.5	Lead-free TQFP	100	64	C
	LC4064V-25TN48C	64	3.3	2.5	Lead-free TQFP	48	32	C
	LC4064V-5TN48C	64	3.3	5	Lead-free TQFP	48	32	C
	LC4064V-75TN48C	64	3.3	7.5	Lead-free TQFP	48	32	C
	LC4064V-25TN44C	64	3.3	2.5	Lead-free TQFP	44	30	C
	LC4064V-5TN44C	64	3.3	5	Lead-free TQFP	44	30	C
	LC4064V-75TN44C	64	3.3	7.5	Lead-free TQFP	44	30	C
LC4128V	LC4128V-27TN144C	128	3.3	2.7	Lead-free TQFP	144	96	C
	LC4128V-5TN144C	128	3.3	5	Lead-free TQFP	144	96	C
	LC4128V-75TN144C	128	3.3	7.5	Lead-free TQFP	144	96	C
	LC4128V-27TN128C	128	3.3	2.7	Lead-free TQFP	128	92	C
	LC4128V-5TN128C	128	3.3	5	Lead-free TQFP	128	92	C
	LC4128V-75TN128C	128	3.3	7.5	Lead-free TQFP	128	92	C
	LC4128V-27TN100C	128	3.3	2.7	Lead-free TQFP	100	64	C
	LC4128V-5TN100C	128	3.3	5	Lead-free TQFP	100	64	C
	LC4128V-75TN100C	128	3.3	7.5	Lead-free TQFP	100	64	C

## ispMACH 4000V (3.3V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-5TN48I	32	3.3	5	Lead-free TQFP	48	32	I
	LC4032V-75TN48I	32	3.3	7.5	Lead-free TQFP	48	32	I
	LC4032V-10TN48I	32	3.3	10	Lead-free TQFP	48	32	I
	LC4032V-5TN44I	32	3.3	5	Lead-free TQFP	44	30	I
	LC4032V-75TN44I	32	3.3	7.5	Lead-free TQFP	44	30	I
	LC4032V-10TN44I	32	3.3	10	Lead-free TQFP	44	30	I
LC4064V	LC4064V-5TN100I	64	3.3	5	Lead-free TQFP	100	64	I
	LC4064V-75TN100I	64	3.3	7.5	Lead-free TQFP	100	64	I
	LC4064V-10TN100I	64	3.3	10	Lead-free TQFP	100	64	I
	LC4064V-5TN48I	64	3.3	5	Lead-free TQFP	48	32	I
	LC4064V-75TN48I	64	3.3	7.5	Lead-free TQFP	48	32	I
	LC4064V-10TN48I	64	3.3	10	Lead-free TQFP	48	32	I
	LC4064V-5TN44I	64	3.3	5	Lead-free TQFP	44	30	I
	LC4064V-75TN44I	64	3.3	7.5	Lead-free TQFP	44	30	I
LC4128V	LC4128V-5TN144I	128	3.3	5	Lead-free TQFP	144	96	I
	LC4128V-75TN144I	128	3.3	7.5	Lead-free TQFP	144	96	I
	LC4128V-10TN144I	128	3.3	10	Lead-free TQFP	144	96	I
	LC4128V-5TN128I	128	3.3	5	Lead-free TQFP	128	92	I
	LC4128V-75TN128I	128	3.3	7.5	Lead-free TQFP	128	92	I
	LC4128V-10TN128I	128	3.3	10	Lead-free TQFP	128	92	I
	LC4128V-5TN100I	128	3.3	5	Lead-free TQFP	100	64	I
	LC4128V-75TN100I	128	3.3	7.5	Lead-free TQFP	100	64	I
	LC4128V-10TN100I	128	3.3	10	Lead-free TQFP	100	64	I